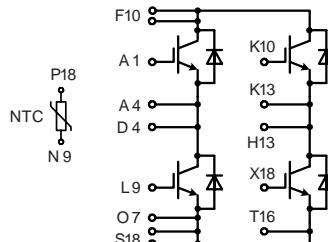


IGBT Modules in ECO-PAC 2

H-Bridge configuration

Short Circuit SOA Capability
Square RBSOA
 $I_{C25} = 69 \text{ A}$
 $V_{CES} = 600 \text{ V}$
 $V_{CE(\text{sat})\text{typ.}} = 2.3 \text{ V}$

Preliminary data sheet



Pin arrangement see outlines

IGBTs

Symbol	Conditions	Maximum Ratings		
V_{CES}	$T_{VJ} = 25^\circ\text{C}$ to 150°C	600		V
V_{GES}		± 20		V
I_{C25}	$T_C = 25^\circ\text{C}$	69		A
I_{C80}	$T_C = 80^\circ\text{C}$	48		A
I_{CM}	$V_{GE} = \pm 15 \text{ V}; R_G = 22 \Omega; T_{VJ} = 125^\circ\text{C}$ RBSOA, Clamped inductive load; $L = 100 \mu\text{H}$	100		A
V_{CEK}		V_{CES}		
t_{sc} (SCSOA)	$V_{CE} = V_{CES}; V_{GE} = \pm 15 \text{ V}; R_G = 22 \Omega; T_{VJ} = 125^\circ\text{C}$ non-repetitive	10	μs	
P_{tot}	$T_C = 25^\circ\text{C}$	208		W

Symbol	Conditions	Characteristic Values		
		($T_{VJ} = 25^\circ\text{C}$, unless otherwise specified)		
		min.	typ.	max.
$V_{CE(\text{sat})}$	$I_C = 75 \text{ A}; V_{GE} = 15 \text{ V}; T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$	2.3 2.8	2.8 V	V
$V_{GE(\text{th})}$	$I_C = 1 \text{ mA}; V_{GE} = V_{CE}$	4.5		6.5 V
I_{CES}	$V_{CE} = V_{CES}; V_{GE} = 0 \text{ V}; T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$		0.8 mA 4.4 mA	
I_{GES}	$V_{CE} = 0 \text{ V}; V_{GE} = \pm 20 \text{ V}$		100 nA	
$t_{d(on)}$ t_r $t_{d(off)}$ t_f E_{on} E_{off}	Inductive load, $T_{VJ} = 125^\circ\text{C}$ $V_{CE} = 300 \text{ V}; I_C = 40 \text{ A}$ $V_{GE} = 15/0 \text{ V}; R_G = 22 \Omega$	50 55 300 30 1.8 1.4	ns ns ns ns mJ mJ	
C_{ies}	$V_{CE} = 25 \text{ V}; V_{GE} = 0 \text{ V}; f = 1 \text{ MHz}$	2.8		nF
R_{thJC} R_{thJH}	(per IGBT) with heatsink compound (0.42 K/m.K; 50 μm)	1.2	0.6 K/W K/W	

IXYS reserves the right to change limits, test conditions and dimensions.

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Reverse diodes (FRED)

Symbol	Conditions	Maximum Ratings		
I _{F25}	T _C = 25°C	56	A	
I _{F80}	T _C = 80°C	35	A	

Symbol	Conditions	Characteristic Values		
		min.	typ.	max.
V _F	I _F = 40 A; T _{VJ} = 25°C T _{VJ} = 125°C	2.32 1.58	2.59	V
I _{RM} t _{rr}	I _F = 30 A; dI _F /dt = 500 A/μs; T _{VJ} = 125°C V _R = 300 V; V _{GE} = 0 V	15 70	ns	A
R _{thJC} R _{thJH}	with heatsink compound (0.42 K/m.K; 50 μm)	2.6	1.3	K/W

Temperature Sensor NTC

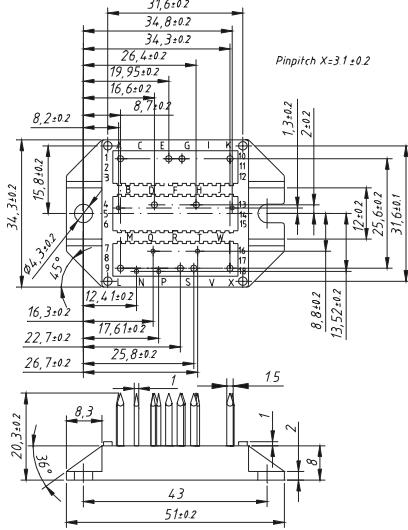
Symbol	Conditions	Characteristic Values		
		min.	typ.	max.
R ₂₅	T = 25°C	455	470	485 kΩ
B _{25/50}			3474	K

Module

Symbol	Conditions	Maximum Ratings		
T _{VJ}		-40...+150		°C
T _{stg}		-40...+150		°C
V _{ISOL}	I _{ISOL} ≤ 1 mA; 50/60 Hz	3000		V~
M _d	mounting torque (M4)	1.5 - 2.0 14 - 18	Nm lb.in.	
a	Max. allowable acceleration	50		m/s ²

Symbol	Conditions	Characteristic Values		
		min.	typ.	max.

Dimensions in mm (1 mm = 0.0394")



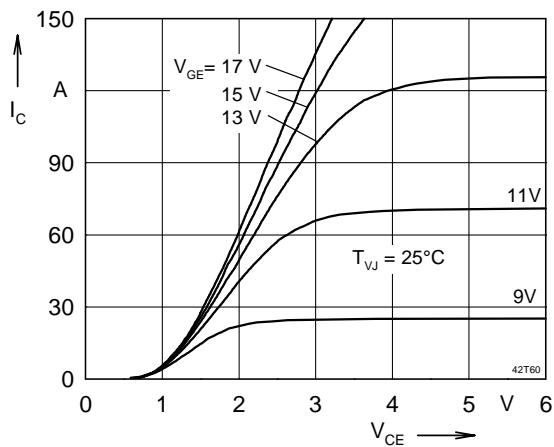


Fig. 1 Typ. output characteristics

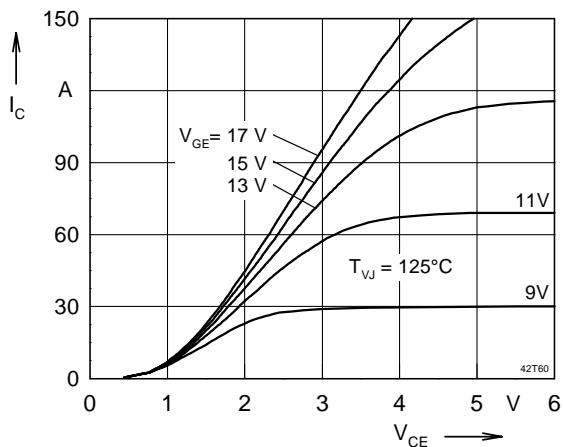


Fig. 2 Typ. output characteristics

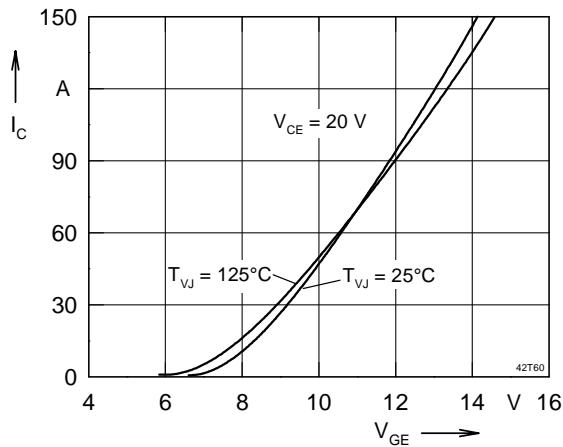


Fig. 3 Typ. transfer characteristics

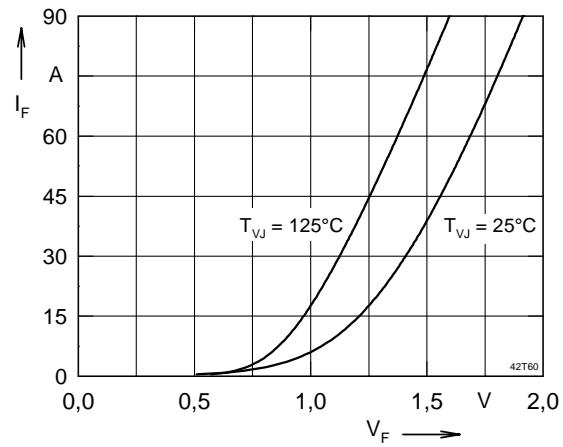


Fig. 4 Typ. forward characteristics of free wheeling diode

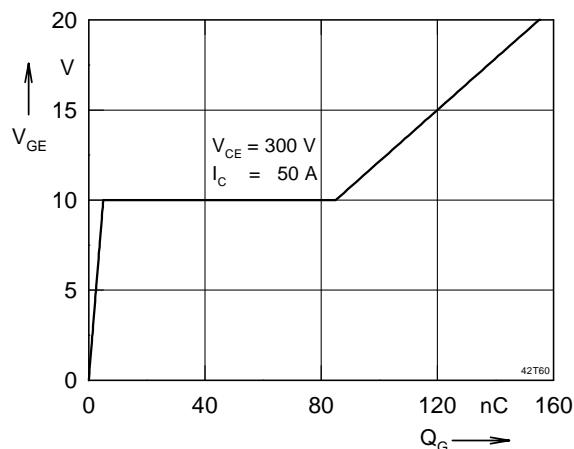


Fig. 5 Typ. turn on gate charge

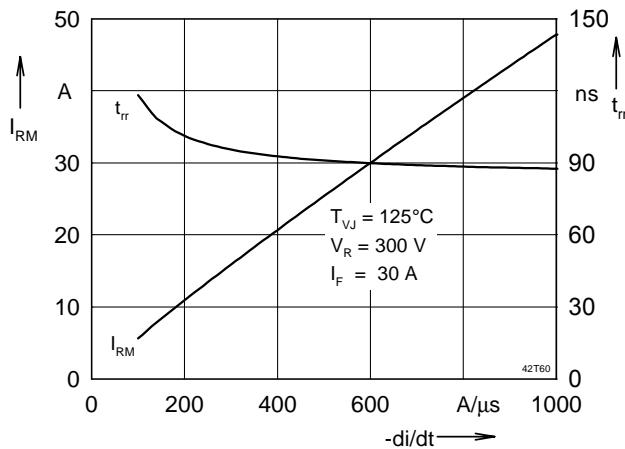


Fig. 6 Typ. turn off characteristics of free wheeling diode

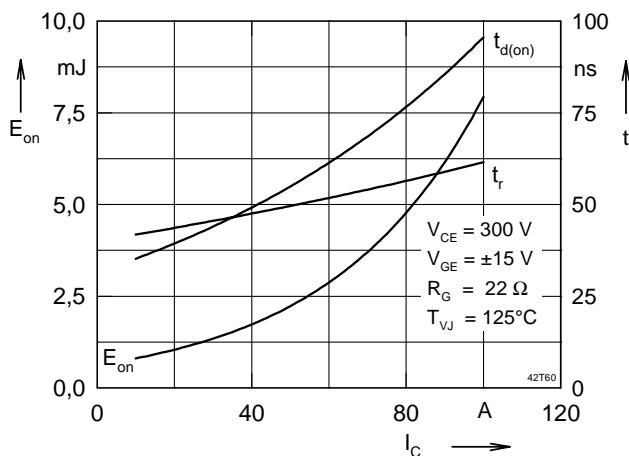


Fig. 7 Typ. turn on energy and switching

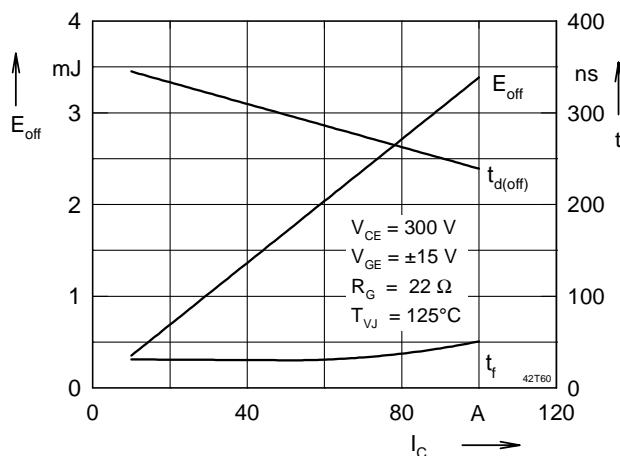


Fig. 8 Typ. turn off energy and switching times versus collector current times versus collector current

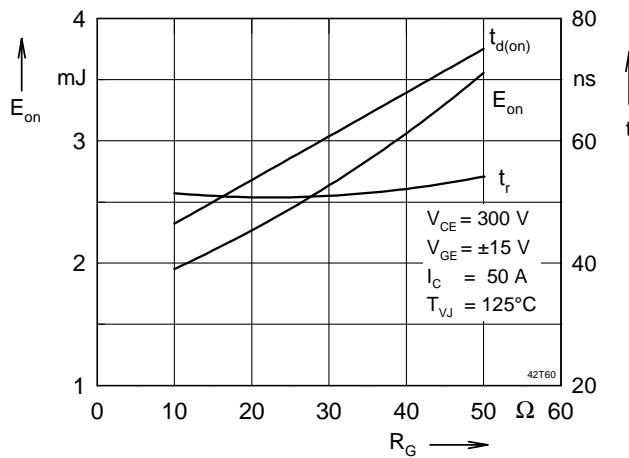


Fig. 9 Typ. turn on energy and switching

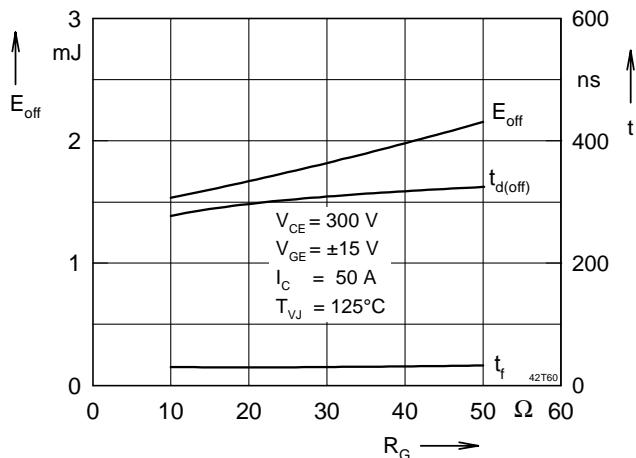


Fig. 10 Typ. turn off energy and switching times versus gate resistor times versus gate resistor

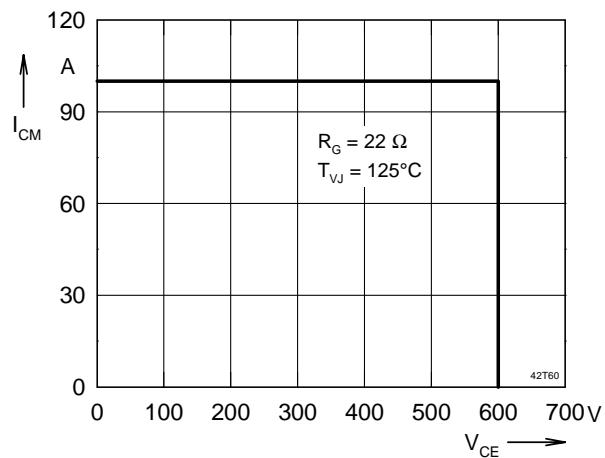


Fig. 11 Reverse biased safe operating area

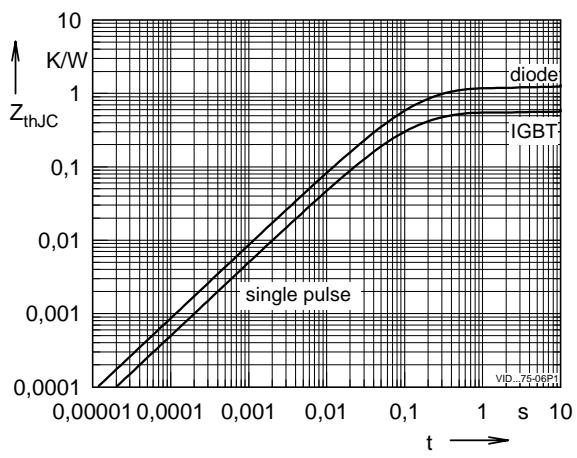


Fig. 12 Typ. transient thermal impedance RBSOA